IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A substrate ~~layered wiring device~~ comprising:

a dielectric core member;

a first plurality of dielectric lamination layers on a first side of the core member;

a second plurality of conductive layers on the first side of the core member;

a first number of dielectric lamination layers on a second side of the core member, wherein the first number is less than the first plurality; and

a second number of conductive layers on the second side of the core member, wherein the second number is less than the second plurality

~~a plurality of electrical conduction members defining at least one electrical conduction path though a layered substrate, the at least one electrical conduction path having substantial impedance continuity maintained within a predefined limit therealong~~.

2. (Currently Amended) A substrate ~~layered wiring device~~ as claimed in claim 1~~, the layered substrate including a dielectric core member, the substantial impedance continuity accomplished at least in part by at least one of: only one electrical conduction path lamination layer on opposing sides of the dielectric core member; a different number of electrical conduction path lamination layers on opposite sides of the dielectric core member; a different dielectric separation distance between electrical conduction path lamination layers on either side of the dielectric core member in comparison to other dielectric separation distances of electrical conduction path lamination layers of the layered substrate; and a~~ wherein the dielectric core member comprises material of different dielectric permittivity ~~of a material of the dielectric core member~~ in comparison to a permittivity of [[a]] material of dielectric lamination layers of the ~~layered~~ substrate.

3. (Currently Amended) A substrate ~~layered wiring device~~ as claimed in claim 1, ~~the layered substrate being a laminated substrate having a dielectric core member and at least one dielectric~~

~~lamination layer,~~ wherein the dielectric core member has ~~having one of:~~ a thickness that ~~which~~ is thicker than a thickness of ~~the~~ at least one dielectric lamination layer, and wherein the dielectric core member includes material of a different dielectric permittivity than ~~that~~ that of [[a]] material of the at least one dielectric lamination layer~~, at least one electrical conduction member of the at least one electrical conduction path being disposed on a first side of the dielectric core member, while other ones of the plurality of electrical conduction members having a potential parasitic capacitance relationship with the at least one electrical conduction member being disposed on an opposite side of the dielectric core member~~.

4. (Canceled)

5. (Currently Amended) A substrate ~~layered wiring device~~ as claimed in claim 4, wherein the second number of conductive layers includes ~~the at least one electrical conduction member including~~ at least one of a conductive bump/ball, trace, pad and via-pad member of a grid array mounting arrangement.

6-7. (Canceled)

8. (Currently Amended) A system comprising:

a layered substrate including

a dielectric core member;

a first plurality of dielectric lamination layers on a first side of the core member;

a second plurality of conductive layers on the first side of the core member;

a first number of dielectric lamination layers on a second side of the core member, wherein the first number is less than the first plurality; and

a second number of conductive layers on the second side of the core member, wherein the second number is less than the second plurality

~~a layered wiring device including a plurality of electrical conduction members defining at least one electrical conduction path though a layered substrate, the at least one electrical conduction path having substantial impedance continuity maintained within a predefined limit therealong~~.

9. (Currently Amended) A system as claimed in claim 8, wherein the dielectric core member comprises material of a different dielectric permittivity in comparison to a permittivity of material of dielectric lamination layers of the substrate ~~the layered substrate including a dielectric core member, the substantial impedance continuity accomplished at least in part by at least one of: only one electrical conduction path lamination layer on opposing sides of the dielectric core member; a different number of electrical conduction path lamination layers on opposite sides of the dielectric core member; a different dielectric separation distance between electrical conduction path lamination layers on either side of the dielectric core member in comparison to other dielectric separation distances of electrical conduction path lamination layers of the layered substrate; and, a different dielectric permittivity of a material of the dielectric core member in comparison to a permittivity of a material of dielectric lamination layers of the layered substrate~~.

10. (Currently Amended) A system as claimed in claim 8, wherein ~~the layered substrate being a laminated substrate having a dielectric core member and at least one dielectric lamination layer,~~ the dielectric core member has ~~having one of:~~ a thickness that ~~which~~ is thicker than a thickness of ~~the~~ at least one dielectric lamination layer, and wherein the dielectric core member includes material of a different dielectric permittivity than ~~that~~ that of a material of the at least one dielectric lamination layer, ~~at least one electrical conduction member of the at least one electrical conduction path being disposed on a first side of the dielectric core member, while other ones of the plurality of electrical conduction members having a potential parasitic capacitance relationship with the at least one electrical conduction member being disposed on an opposite side of the dielectric core member~~.

11. (Canceled)

12. (Currently Amended) A system as claimed in claim 11, wherein the second number of conductive layers includes ~~at least one electrical conduction member including~~ at least one of a conductive bump/ball, trace, pad and via-pad member of a grid array mounting arrangement.

13-21. (Canceled)

22. (New) The substrate as claimed in claim 1, wherein the first number is zero.

23. (New) The substrate as claimed in claim 1, wherein the second number is one.

24. (New) The substrate as claimed in claim 8, wherein the first number is zero.

25. (New) The system as claimed in claim 8, wherein the second number is one.